

**DECLARATION FOR PATENT APPLICATION AND APPOINTMENT OF ATTORNEY**

As a below named inventor, I hereby declare that I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention (Design, if applicable) entitled:

Title: UNDER BUMP METALLIZATION STRUCTURE OF A SEMICONDUCTOR WAFER

the specification of which (check at least one of the first three boxes below, as applicable):

<input checked="" type="checkbox"/>	is attached hereto.	
<input type="checkbox"/>	was filed on (day-month-year)	as U.S. Application Number
<input type="checkbox"/>	was filed on (day-month-year)	as PCT Application Number
<input type="checkbox"/>	and (if applicable) was amended on (day-month-year)	

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate listed on the Application Data Sheet, and have also identified on the Application Data Sheet any foreign application for patent or inventor's certificate having a filing date before that of each application on which priority is claimed.

I hereby claim the benefit under Title 35 U.S. Code §119(e) of any U.S. provisional applications listed on the Application Data Sheet.

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) or PCT international application(s) designating The United States of America listed on the Application Data Sheet, and, insofar as the subject matter of each of the claims of this application is not disclosed in that/those prior application(s) in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application(s) and the national or PCT international filing date of this application.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

**POWER OF ATTORNEY:** I (We) hereby appoint as my (our) attorneys, with full powers of substitution and revocation, to prosecute this application including the submission and amendment of an application data sheet (37 CFR §1.76), to take instructions from my (our) agent, to receive all communications at the address stated on the Application Data Sheet, and transact all business in the Patent and Trademark Office connected therewith: J. Ernest Kenney, Reg. No. 19,179; Eugene Mar, Reg. No. 25,893; Richard E. Fichter, Reg. No. 26,382; Thomas J. Moore, Reg. No. 28,974; Joseph DeBenedictis, Reg. No. 28,502; and Benjamin E. Urcia, Reg. No. 33,805; each of Bacon & Thomas, PLLC, and

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Date 2/25/04	Signature Min-Lung Huang

☐ See following page(s) for additional joint inventors.

(02Nov2001)